

PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	Patent Security Agreement
CONVEYING PARTY DATA	
Name	Execution Date
Avantor Performance Materials, Inc.	06/24/2011
RECEIVING PARTY DATA	
Name:	Credit Suisse AG, Cayman Islands Branch
Street Address:	Eleven Madison Avenue
City:	New York
State/Country:	NEW YORK
Postal Code:	10010
PROPERTY NUMBERS Total: 57	
Property Type	Number
Patent Number:	6203679
Patent Number:	5217619
Patent Number:	5308745
Patent Number:	6749998
Patent Number:	6326130
Patent Number:	5466389
Patent Number:	5498293
Patent Number:	5576217
Patent Number:	5989353
Patent Number:	6585825
Patent Number:	6465403
Patent Number:	6599370
Patent Number:	6311134
Patent Number:	6899818
Patent Number:	6875817

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PATENT
REEL: 026499 FRAME: 0256

CH \$2280.00 6203679

Patent Number:	7393819
Patent Number:	7247208
Patent Number:	7718591
Patent Number:	7419945
Patent Number:	7671001
Patent Number:	7470767
Patent Number:	7928046
Patent Number:	7521406
Patent Number:	7767636
Patent Number:	7754668
Patent Number:	7825078
Patent Number:	7947639
Patent Number:	7951764
Patent Number:	7799749
Patent Number:	7375188
Application Number:	11813434
Application Number:	11630603
Application Number:	11817874
Application Number:	12565172
Application Number:	11910281
Application Number:	11521246
Application Number:	12046582
Application Number:	12522605
Application Number:	12522716
Application Number:	12596921
Application Number:	12600369
Application Number:	12619259
Application Number:	10515372
Application Number:	61155309
Application Number:	61357146
Application Number:	12811257
Application Number:	61401808
Application Number:	12737663
Application Number:	12998296
Application Number:	12998499

	13066889
Application Number:	61518305
Application Number:	61518258
Application Number:	12998655
Application Number:	12998659
Application Number:	12998656
Application Number:	61519902

CORRESPONDENCE DATA	
Fax Number:	(917)777-4104
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	212-735-3000
Email:	robert.wise@skadden.com
Correspondent Name:	Skadden Arps Slate Meagher & Flom LLP
Address Line 1:	4 Times Square
Address Line 2:	Attn: Shivram Sankar
Address Line 4:	New York, NEW YORK 10036

ATTORNEY DOCKET NUMBER:	217730/2332
NAME OF SUBMITTER:	Shivram Sankar

Total Attachments: 8 source=Patent Security Agreement#page1.tif source=Patent Security Agreement#page2.tif source=Patent Security Agreement#page3.tif source=Patent Security Agreement#page4.tif source=Patent Security Agreement#page5.tif source=Patent Security Agreement#page6.tif source=Patent Security Agreement#page7.tif source=Patent Security Agreement#page8.tif

PATENT SECURITY AGREEMENT

PATENT SECURITY AGREEMENT dated as of June 24, 2011 (this "**Agreement**"), among AVANTOR PERFORMANCE MATERIALS, INC., a New Jersey corporation (the "**Grantor**"), located at 222 Red School Lane, Phillipsburg, NJ 08865, and CREDIT SUISSE AG, CAYMAN ISLANDS BRANCH ("**CS**"), as collateral agent (in such capacity, the "**Collateral Agent**").

WHEREAS, Avantor Performance Materials Holdings, Inc., a Delaware corporation (the "**Borrower**") previously entered into a Credit Agreement, dated as of October 8, 2010 (the "**Existing Credit Agreement**"), among the Borrower, the Lenders and CS, as the Administrative Agent (in such capacity, the "**Administrative Agent**", referred to herein collectively with the Collateral Agent as "**Agent**"), the Collateral Agent and the other parties thereto, pursuant to which the Lenders have extended, and have agreed to extend, credit to the Borrower; and

WHEREAS, the Grantor, as a direct wholly-owned subsidiary of Borrower, entered into (a) a Guarantee and Collateral Agreement, dated as of October 8, 2010 (the "**Guarantee and Collateral Agreement**") by and among the Borrower, the Grantor, the Collateral Agent and the other parties thereto and (b) a Patent Security Agreement, dated as of October 8, 2010, by and among the Grantor and the Collateral Agent, which was recorded with the United States Patent and Trademark Office at Reel 025114/ Frame 0208; and

WHEREAS, the Borrower desires to enter into (A) the Amendment Agreement, dated as of the date hereof (the "**Amendment Agreement**") among the Borrower, the Grantor, the other Loan Parties and the Agent, which Amendment Agreement, among other things, amends and restates the Existing Credit Agreement in the form of the Amended and Restated Credit Agreement (as amended, supplemented or otherwise modified from time to time, the "**Amended and Restated Credit Agreement**") and (B) the Incremental Term Loan Assumption Agreement, dated as of the date hereof (the "**Incremental Agreement**"), among the Borrower, the Grantor, the other Loan Parties and the Administrative Agent. The Lenders have agreed to extend credit to the Borrower subject to the terms and conditions set forth in the Amendment Agreement, the Amended and Restated Credit Agreement and the Incremental Agreement. The obligations of the Lenders to extend such credit are conditioned upon, among other things, the execution and delivery of this Agreement. The Grantor is a direct, wholly-owned subsidiary of the Borrower, and will derive substantial benefits from the extensions of credit to the Borrower pursuant to the Amendment Agreement, the Amended and Restated Credit Agreement and the Incremental Agreement, and accordingly is willing to (i) acknowledge and agree that the Guarantee and Collateral Agreement remains in effect, (ii) confirm and ratify the guarantees and liens granted thereunder and (iii) execute and deliver this Agreement to induce the Lenders to extend such credit.

Accordingly, in consideration of the mutual agreements herein contained and other good and valuable consideration, the sufficiency and receipt of which are hereby acknowledged, the parties hereto agree as follows:

SECTION 1. Terms. Each capitalized term used but not defined in this Agreement has the meaning given or ascribed to it in the Guarantee and Collateral Agreement. The rules of construction specified in Section 1.01(b) of the Guarantee and Collateral Agreement also apply to this Agreement.

SECTION 2. Grant of Security Interest. As security for the payment or performance, as the case may be, in full of the Obligations, the Grantor hereby pledges to the Collateral Agent, its successors and assigns, for the ratable benefit of the Secured Parties, and hereby grants to the Collateral Agent, its successors and assigns, for the ratable benefit of the Secured Parties, a security interest in all right, title or interest in or to any and all of the following assets and properties now owned or at any time hereafter acquired by the Grantor or in which the Grantor now has or at any time in the future may acquire any right, title or interest (collectively, the ***“Patent Collateral”***):

(a) all patents issued by the United States or the equivalent thereof in any other country, and all applications for patents of the United States or the equivalent thereof in any other country, including issued patents and pending applications in the United States Patent and Trademark Office (or any successor or any similar offices in any other country), including those listed on Schedule I;

(b) all reissues, continuations, divisions, continuations-in-part, renewals or extensions thereof, and the inventions disclosed or claimed therein, including the right to make, use and/or sell the inventions disclosed or claimed therein ((a) and (b) collectively, the ***“Patents”***); and

(c) all Proceeds and products of any and all of the foregoing, all Supporting Obligations and all collateral security and guarantees given by any Person with respect to any of the foregoing.

SECTION 3. Recordation. This Agreement has been executed and delivered by the Grantor for the purpose of recording the grant of security interest herein with the United States Patent and Trademark Office. The Grantor authorizes and requests that the Commissioner of Patents and Trademarks record this Agreement.

SECTION 4. Guarantee and Collateral Agreement. The security interests granted to the Collateral Agent herein are granted in furtherance, and not in limitation of, the security interests granted to the Collateral Agent pursuant to the Guarantee and Collateral Agreement. The Grantor hereby acknowledges and affirms that the rights and remedies of the Collateral Agent with respect to the Patent Collateral are more fully set forth in the Guarantee and Collateral Agreement, the terms and provisions of which are hereby incorporated herein by reference as if fully set forth herein. In the event of any conflict between the terms of this Agreement and the Guarantee and Collateral Agreement, the terms of the Guarantee and Collateral Agreement shall govern, and for the avoidance of doubt, Patent Collateral shall not include any Excluded Assets.

SECTION 5. Counterparts. This Agreement may be executed in counterparts (and by different parties hereto on different counterparts), each of which shall constitute an original but all of which when taken together shall constitute a single contract. Delivery of an executed

signature page to this Agreement by facsimile transmission shall be as effective as delivery of a manually signed counterpart of this Agreement.

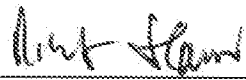
SECTION 6. Further Assurances. The Grantor further agrees to execute and deliver to the Collateral Agent any and all further documents and instruments, and do any and all further acts which the Collateral Agent (or the Collateral Agent's agents or designees) reasonably requests in order to confirm this grant of security interest in and to the Patent Collateral.

SECTION 7. Applicable Law. THIS AGREEMENT SHALL BE CONSTRUED IN ACCORDANCE WITH AND GOVERNED BY THE LAWS OF THE STATE OF NEW YORK.

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IN WITNESS WHEREOF, the parties hereto have duly executed this Agreement
as of the day and year first above written.

AVANTOR PERFORMANCE
MATERIALS, INC.

By: 
Name: Robert Harrer
Title: Executive Vice President, Chief
Financial Officer, Chief Administrative
Officer and Treasurer

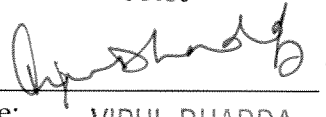
[SIGNATURE PAGE TO PATENT SECURITY AGREEMENT]

PATENT
REEL: 026499 FRAME: 0262

Acknowledged and Agreed by:

CREDIT SUISSE AG, CAYMAN ISLANDS BRANCH

By: 
Name: Jay Chall
Title: Director

By: 
Name: VIPUL DHADDA
Title: ASSOCIATE

[SIGNATURE PAGE TO PATENT SECURITY AGREEMENT]

PATENT
REEL: 026499 FRAME: 0263

SCHEDULE I TO PATENT SECURITY AGREEMENT

Patents and Patent Applications

Title	Appl. No.	Filing Date	Patent No.	Issue Date	Status
Electrophoresis Gel Container	09/251129	16-Feb-99	6203679	20-May-01	Granted
Liquid-Solid Extraction Apparatus and Method of Using Same	846895	06-Mar-92	5217619	08-Jun-93	Granted
Alkaline-Containing Photoresist Stripping Compositions Producing Reduced Metal Corrosion with Cross-Linked or Hardened Resist Resins	972511	06-Nov-92	5308745	03-May-94	Granted
Photoresist Strippers Containing Reducing Agents to Reduce Metal Corrosion	09/968665	02-Oct-01	6749998	15-Jun-04	Granted
Photoresist Strippers Containing Reducing Agents to Reduce Metal Corrosion	08/133680	07-Oct-93	6326130	04-Dec-01	Granted
pH Adjusted Surfactant-Containing Alkaline Cleaner Composition for Cleaning Microelectronics Substrates	230132	20-Apr-94	5466389	14-Nov-95	Granted
Cleaning Wafer Substrates of Metal Contamination While Maintaining Wafer Smoothness	264858	23-Jun-94	5498293	12-Mar-96	Granted
Solid Phase Micro-Extraction of Trace Amounts of Organic Analytes	396124	28-Feb-95	5576217	19-Nov-96	Granted
Cleaning Wafer Substrates of Metal Contamination While Maintaining Wafer Smoothness	08/729565	11-Oct-96	5989353	23-Nov-99	Granted
Stabilized Alkaline Compositions for Cleaning Microelectronic Substrates	09/688559	16-Oct-00	6585825	01-Jul-03	Granted
Silicate-Containing Alkaline Compositions for Cleaning Microelectronic Substrates	09/701114	17-Nov-00	6465403	15-Oct-02	Granted
Stabilized Alkaline Compositions for Cleaning Microelectronic Substrates	09/859142	16-May-01	6599370	29-Jul-03	Granted
Process and Apparatus for Comparing Chemical Products	09/247058	09-Feb-99	6311134	30-Oct-01	Granted
Method and Composition for Removing Sodium-Containing Material from Microcircuit Substrates	10/220720	04-Sep-02	6899818	31-May-05	Granted
Functionalized Polymeric Media for Separation of Analytes	10/250570	12-Feb-03	6875817	05-Apr-05	Granted
Ammonia-Free Alkaline Microelectronic Cleaning Compositions with Improved Substrate Compatibility	10/483037	06-Jan-04	7393819	01-Jul-08	Granted
Microelectronic Cleaning Compositions Containing Ammonia-Free Fluoride Salts for Selective Photoresist Stripping and Plasma Ash	10/483036	06-Jan-04	7247208	24-Jul-07	Granted
Microelectronic Cleaning Compositions Containing Ammonia-Free Fluoride Salts for Selective Photoresist Stripping and Plasma Ash	11/762087	13-Jun-07	7718591	18-May-10	Granted

Title	Appl. No.	Filing Date	Patent No.	Issue Date	Status
Microelectronic Cleaning Compositions Containing Oxidizers and Organic Solvents	10/515392	22-Nov-04	7419945	02-Sep-08	Granted
Alkaline, Post Plasma Etch or Post Etch/Ash Residue Removers and Photoresist Strippers Containing Metal-Halide Corrosion Inhibitors	10/572860	22-Mar-06	7671001	02-Mar-10	Granted
Preparation of Ultrapure Polymeric Articles	11/631586	04-Jan-07	7470767	30-Dec-08	Granted
Preparation and Use of Mixed Mode Polymeric Chromatographic Media for Bioseparations	11/813434	06-Jul-07			Published
Stripping and Cleaning Compositions for Microelectronics	11/349635	08-Feb-06	7928046	19-Apr-11	Granted
Microelectric Cleaning Composition Containing Halogen Oxygen Acids, Salts and Derivatives	10/982330	05-Nov-04	7521406	21-Apr-09	Granted
Nanoelectronic and Microelectronic Cleaning Compositions	10/584827	27-Jun-06	7767636	03-Aug-10	Granted
Compositions for the Removal of Post-Etch and Ashed Photoresist Residue and Bulk Photoresist	11/911346	12-Oct-07	7754668	13-Jul-10	Granted
Composition for Cleaning Microelectronic Substrates	11/630603	20-Dec-06			Published
Non-Aqueous Stripping Composition Containing Fructose	11/630602	20-Dec-06	7825078	27-Oct-06	Granted
Non-Aqueous, Non-Corrosive Microelectronic Cleaning Compositions Containing Polymeric Corrosion Inhibitors	11/719690	18-May-07	7947639	24-May-11	Pending
Compositions for Cleaning Ion Implanted Photoresist in Front End of Line Applications	11/817874	06-Sep-07			Published
High Efficiency Chromatography Column With Re-Usable End Cap	12/565172	23-Sep-09			Published
Non-Aqueous, Non-Corrosive Microelectronic Cleaning Compositions	11/720084	24-May-07	7951764	31-May-11	Pending
Non-Aqueous Photoresist Stripper That Inhibits Galvanic Corrosion	11/910281	01-Oct-07			Published
Stabilized, Non-Aqueous Cleaning Compositions for-Microelectronics Substrates	12/161886	23-Jul-08	7799749	21-Sep-10	Granted
Purified Vegetarian Protein A And Process For Production Thereof	11/521246	14-Sep-06			Published
Purified Vegetarian Protein A And Process For Production Thereof Vegetarian	11/194093	29-Jul-05	7375188	20-May-08	Granted
Purified Vegetarian Protein A And Process For Production Thereof	12/046582	12-Mar-08			Published
Chromatographic Media and Chromatographic Equipment Storage Solutions and Use Thereof	12/522605	09-Jul-09			Published
Peroxide Activated Oxometalate Based Formulations for Removal of Etch Residues	12/522716	10-Jul-09			Published
Polysilicon Planarization Solution For Planarizing Low Temperature Poly-Silicon Thin Film Panels	12/596921	21-Oct-09			Published
Directly Compressible High Functionality Granular Microcrystalline Cellulose Based Excipient, Manufacturing Process and Use Thereof	12/600369	16-Nov-09			Published

Title	Appl. No.	Filing Date	Patent No.	Issue Date	Status
Directly Compressible Granular Microcrystalline Cellulose Based Excipient, Manufacturing Process and Use Thereof	12/619259	16-Nov-09			Published
Microelectronic Cleaning and Arc Remover Compositions	10/515372	22-Nov-04			Published
Multipurpose Acidic Organic Solvent Based Microelectronic Cleaning Composition	61/155309	25-Feb-09			Pending
Metal Sulfide Deposition Using Alkylated Thioureas	61/357146	22-Jun-10			Pending
Post Plasma Etch/Ash Residue and Silicon-Based Anti-Reflective Coating Remover Compositions Containing Tetrafluoroborate Ion	12/811257	30-Jun-10			Published
Chemical Solutions for Texturing of Multicrystalline Silicone Wafers for Solar Cell Manufacturing	61/401808	19-Aug-10			Pending
Sustained Release Composition	12/737663	04-Feb-11			Published
Aqueous Acidic Formulations for Copper Oxide Etch Residue Removal and Prevention of Copper	12/998296	06-Apr-11			Pending
Gluconic Acid-Containing Microelectronics Stripping and Cleaning Composition	12/998499	27-Apr-11			Pending
Non-Aqueous, Non-Corrosive Photoresist Stripper Containing Polymer Having Multiple Amino and/or Hydroxyl Functional Groups	13/066889	27-Apr-11			Pending
Separation of Protein Monomers and Aggregates by Weak Anion Exchangers	61/518305	03-May-11			Pending
A Novel Chromatographic Media Based on Alkylamine Spacer, Synthesis and Use Thereof	61/518258	03-May-11			Pending
Directly Compressible High Functionality Granular Dibasic Calcium Phosphate Based Co-Processed Excipient.	12/998655	16-May-11			Pending
Directly Compressible Granular Microcrystalline Cellulose Co-Processed Excipient and Process To	12/998659	16-May-11			Pending
New Chromatographic Media Based On Phenoxy Alkyl And Alkoxy-Or Phenoxy-Phenyl Alkyl Ligands	12/998656	16-May-11			Pending
Solvent Based Polymer Removal Chemistry With Enhanced Compatability With Copper Metallization And Porous Low-K Dielectrics	61/519902	01-Jun-11			Pending